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end

horizontal direction and rotates forward and reversely, thereby delivering the wafers W in the cassette C one after another and transporting them into the probing chamber 12. A sub-chuck 16 for pre-aligning each wafer W is provided near the tweezers 15. As the sub-chuck 16 receives each wafer W from the tweezers 15 and rotates in the forward direction and the reverse direction in a θ -direction, it pre-aligns the wafer W on the basis of its orientation flat.

Page 2, please delete the paragraph beginning at line 16 and ending at page 3, line 11 and substitute therefor:

a2

The probing chamber 12 is provided with a main chuck 17 that carries each wafer W thereon. The main chuck 17 is moved in X- and Y-directions by means of X- and Y-stages 18, 19, respectively, and moved in Z- and θ -directions by means of built-in drive mechanisms. Alignment means 20 is provided in the probing chamber 12. The alignment means 20 serves to align each wafer W with the probes. The alignment means 20 includes an alignment bridge 22 having first image-pickup means (e.g., CCD camera) 21 for imaging the wafer W, a pair of guide rails 23 for guiding the bridge 22 in reciprocation in the Y-direction, and second image-pickup means (e.g., CCD camera, not shown) attached to the main chuck 17. A probe card is provided on the top surface of the probing chamber 12. On the upper surface of the probe card, a test head is connected electrically to the card by means of a connecting ring. A test signal from a tester 34 (see FIG. 1) is transmitted to the probe card via the test head and the connecting ring, and further transmitted from the probe card to the wafer W. The object of inspection is checked for electrical properties in accordance with the test signal.
